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- Designed for NuBus<sup>™</sup> Interface Applications
- Conforms to ANSI/IEEE Std 1196-1987
- **On-Chip Comparator Provides I/D Slot** Identification
- Multiplexed Real-Time and Latched Address/Data
- Designed to Operate With SN74ACT2440 NuBus<sup>™</sup> Controller
- BiCMOS Design Substantially Reduces **Standby Current**
- Dependable Texas instruments Quality and Reliability

#### description

The 'BCT2420 consists of bus transceiver circuits, D-type flip-flops, latches, and control circuitry arranged for multiplexed transmission of address and data information in NuBus<sup>™</sup> applications. An on-chip comparator has been included to detect when a NuBus<sup>™</sup> transfer cycle is requesting the local board. The device conforms to ANSI/IEEE Std 1196-1987 and operates with Texas instruments SN74ACT2440 NuBus™ Controller. In addition, the device is easily configured around ASIC or other PAL<sup>®</sup> -based controllers.



The 'BCT2420 was designed using Texas Instruments BiCMOS process, which features bipolar drive characteristics and greatly reduces the standby power of the device when disabled. This feature is especially valuable when the device is not performing a NuBus™ transaction.

The AEN, DEN and ADEN inputs control the transceiver functions. Three 16-bit I/O ports, A15–A0, D15–D0, and AD15–AD0, provide for address and data transfer. When the NuBus™ performs a write cycle to the local board, address information is saved on the rising edge of ACLK. During the last portion of the NuBus™ write cycle, data information is saved on the rising edge of DCLK.

When the local board is performing a write to the NuBus™, address and data is multiplexed onto the NuBus™ via the A/D line. Address and data can be latched by using the ALE and DLE input lines respectively.

The IDEQ output is used to signal that the local board is being requested by the NuBus™. This output is typically fed to the NuBus<sup>™</sup> controller. IDEQ goes active (low) when AD15–AD12 are low and AD11–AD8 match ID3–ID0. IDEQ stays valid until the next address clock (ACLK) occurs. Internal 10-k $\Omega$  pullup resistors are included on the ID3-ID0 inputs.

The SSEQ output is used to signal the local board that super-slot addresses are being requested. This output is active (low) whenever AD15-AD12 are equal to ID3-AD0, except when ID3-ID0 are all low.

In typical NuBus™ applications, two devices are required to provide the full 32-bit address/data path. Refer to the typical NuBus<sup>™</sup> interface diagram on page 9 for additional information.

The SN74BCT2420 is characterized for operation from 0°C to 70°C.

NuBus is a trademark of Texas Instruments Incorporated. PAL is a registered trademark of Monolithic Memories Inc.



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Function Tables											
	INPUTS										
A15-A0	D15-D0	ALE	DLE	Ā/D	ADEN	AD15-AD0					
Н	Х	L	Х	L	L	L					
L	Х	L	Х	L	L	н					
Х	Х	Н	Х	L	L	QO					
Х	Н	Х	L	Н	L	L					
Х	L	Х	L	Н	L	н					
Х	Х	Х	Н	Н	L	QO					
Х	Х	Х	Х	Х	Н	Z					

	INPUTS		OUTPUTS
AD15-AD0	ACLK, DCLK	AEN, DEN	A15–A0, D15–DO
Н	$\uparrow$	L	L
L	$\uparrow$	L	Н
Х	L	L	QO
Х	Х	н	L

AD15-AD12	ID3-ID0	SSEQ	AD15-AD12	AD11-AD8	IDEQ
EQ ID3-ID0	NE 0	L	EQ 0	EQ ID3-ID0	L
NE ID3-ID0	X	H	X	NE ID3-ID0	H
X	EQ 0	H	NE 0	X	H

NOTE: Symbol ' $Q_0$ ' denotes previous logic state preserved. Symbol 'Z' denotes high-impedance state.



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logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std. 91-1984.



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#### logic diagram





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#### **Terminal Functions**

PIN NAME	DESCRIPTION
A15–A0	Address bus. This 16-bit I/O port is connected to the local board's address bus. When information is transferred between this port and the NuBus <sup>™</sup> port (AD15–AD0), the data is inverted to conform to NuBus <sup>™</sup> specifications.
ACLK	Address clock. This input saves the address portion of NuBus <sup>™</sup> read or write cycles. Data present at the AD15–AD0 inputs is clocked into the address register on the low-to-high transition of ACLK.
Ā/D	Address/data select. This input controls the address/data multiplexer. When $\overline{A}/D$ is driven low, the local address port, A15–A0, is selected as input to the $\overline{AD15}$ – $\overline{AD0}$ outputs. When $\overline{A}/D$ is taken high, the local data port, D15–D0, is selected as input to the $\overline{AD15}$ – $\overline{AD0}$ outputs.
AD15-AD0	Address/data port. This 16-bit active-low I/O port directly interfaces to the NuBus <sup>™</sup> address/data lines. These lines are multiplexed to carry address information at the beginning of a NuBus <sup>™</sup> cycle and data information later in the cycle.
ADEN	Address/data output enable. This active-low input enables the AD15–AD0 outputs. When ADEN is taken high, the AD15–AD0 outputs are in the high impedance state, allowing input from the NuBus™.
AEN	$\frac{\text{Address enable. This active-low input enables the local address outputs. A15-A0, to place data onto the local board. When \overline{\text{AEN}}$ is taken high, the A15-A0 outputs are in the high-impedance state, allowing input from the local address bus.
ALE	Address latch enable. This active-low input controls the latch that holds the address received from the local address bus, A15–A0. When ALE is low, the latch is transparent. When ALE is taken high, the address present at the A15–A0 inputs is latched and remains latched while ALE is held high.
D15–D0	Data bus. This 16-bit I/O port is connected to the local board's data bus. When information is transferred between this port and the NuBus <sup>™</sup> port (AD15–AD0), the data is inverted to conform to NuBus <sup>™</sup> specifications.
DCLK	Data clock. This input saves the data portion of NuBus <sup>™</sup> write cycles. Data present at the AD15–AD0 inputs is clocked into the data register on the low-to-high transition of DCLK.
DEN	Data enable. This active-low input enables the local data port outputs, D15–D0, to place data onto the local board. When DEN is taken high, the D15–D0 outputs are in the high-impedance state, allowing input from the local board.
DLE	Data latch enable. This active-low input controls the latch that holds the data received from the local data bus, D15–D0. When DLE is low, the latch is transparent. When DLE is taken high, the data present at the D15–D0 inputs is latched and remains latched while DLE is held high.
ID3-ID0	Card-slot identification. These four inputs accept binary-coded location information for each NuBus <sup><math>M</math></sup> slot position on the backplane. These four lines are typically hard wired logic levels unique to each NuBus <sup><math>M</math></sup> slot connector. For convenient implementation, the inputs have internal 10-k $\Omega$ pull up resistors that ensure the logic high level when the inputs are left open circuited. The internal comparator uses these inputs to identify when the local hardware card is being accessed.
IDEQ	Identification equal. This active-low output is used to signal that the board is being accessed by the NuBus <sup>™</sup> . IDEQ goes low whenever AD15–AD12 are low and AD11–AD8 match ID3–ID0. Since the internal comparator uses data from the address register, the address register must be clocked before the local board samples IDEQ. IDEQ is valid for the entire NuBus <sup>™</sup> cycle after ACLK.
SSEQ	Super-slot equal. This active-low output is used to signal the local board that super-slot addresses are being requested in the super-slot mode. SSEQ goes low when AD15–AD12 match ID3–ID0 and ID3–ID0 are not all low. Since the internal comparator uses data from the address register, the address register must be clocked before the local board samples SSEQ. SSEQ is valid for the entire NuBus <sup>™</sup> cycle after ACLK.



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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub> (see Note 1)		7V
Input voltage (all inputs and I/O ports)		5.5 V
Operating free-air temperature range	0°C to	o 70°C
Storage temperature range	-65°C to	150°C

<sup>†</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the recommended operating conditions section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. NOTE 1: All voltage values are with respect to GND.

#### recommended operating conditions

	PA	MIN	NOM	MAX	UNIT		
VCC	Supply voltage	4.5	5	5.5	V		
VIH	High-level input voltage	2			V		
VIL	Low-level input voltage				0.8	V	
lau	High lovel input current	Ax, Dx, ADx outputs			-15	m۸	
ЮН	High-level liput current	SSEQ, IDEQ outputs			2.6	ША	
		Ax, Dx, ADx outputs			24	<b>m</b> A	
OL	Low-level input current	SSEQ, IDEQ outputs			16	ma	
fclock	Clock frequency	0		40	MHz		
		ACLK, DCLK high	12.5				
tw	Pulse duration	ACLK, DCLK low	12.5			ns	
		ALE, DLE low	12.5				
		ADx before ACLK↑, DCLK↑	5				
t <sub>su</sub>	Setup time	Ax before ALE 1 5				ns	
		Dx before DLE↑	5			1	
		ADx after ACLK↑, DCLK↑	2				
t <sub>h</sub>	Hold time	Ax after ALE↑	2			ns	
		Dx after DLE↑	2				
TA	Operating free-air temperature		0		70°	°C	



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		-	-					
	PARAMETER	TEST CO	ONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	l <sub>l</sub> = –18 mA			-1.2	V	
		$V_{CC} = 4.5 V \text{ to } 5.5 V,$	I <sub>OH</sub> = -400 μA	V <sub>CC</sub> -1.5				
	Ax, Dx, ADx	V <sub>CC</sub> = 4.5 V,	$I_{OH} = -3 \text{ mA}$	2.8	3.6			
∨он		$V_{CC} = 4.5 V,$	I <sub>OH</sub> = -15 mA	2			V	
		$V_{CC} = 4.5 V \text{ to } 5.5 V,$	I <sub>OH</sub> = -400 μA	V <sub>CC</sub> -2				
	SSEQ, IDEQ	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -2.6 mA	2.4	3.2			
VOL		V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 12 mA		0.25	0.4		
	Ax, Dx, ADx	V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 24 mA		0.35	0.5	V	
		V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 8 mA		0.25	0.4		
	SSEQ, IDEQ	V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 16 mA		0.35	0.5		
Ц		V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			100	μA	
	AEN, DEN, ADEN		V <sub>I</sub> = 2.7 V			20	μA	
цн‡	ID3-ID0	V <sub>CC</sub> = 5.5 V,				-400		
	All other inputs	1				-100		
. +	ID3-ID0					-750		
<sup>1</sup> 1∟+	All other inputs	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$			-200	μΑ	
los§	•	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0 V	-60		-225	mA	
	Enabled	V <sub>CC</sub> = 5.5 V,	V <sub>IL</sub> = 0.5 V, Outputs open		110	160	mA	
lcc	Disabled	$V_{IH} = 3 V,$			30	40		

#### electrical characteristics over recommended operating free-air temperature range

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. <sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current. § Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.



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#### switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		LOAD CONDITIONS						
	PARAMETER	R1, R2, and RL	CL	LOAD CIRCUIT	MIN	IYPI	MAX	UNIT
f <sub>max</sub>	Maximum clock frequency				40			MHz
<sup>t</sup> pd	Propagation time, ACLK $\uparrow$ to Ax ( $\overline{AEN} = L$ )	R1 = 500 Ω, R2 = 500 Ω	50 pF	S1 Open∓		9	16	ns
<sup>t</sup> pd	Propagation time, DCLK $\uparrow$ to Dx (DEN = L)	R1 = 500 Ω, R2 = 500 Ω	50 pF	S1 Open∓		9	16	ns
<sup>t</sup> pd	Propagation time, Ax to $\overline{ADx}$ ( $\overline{ALE} = L$ , $\overline{A}/D = L$ )	R1 = 270 Ω, R2 = 470 Ω	300 pF	S1 Closed§		10	18	ns
<sup>t</sup> pd	Propagation time, Dx to $\overline{ADx}$ ( $\overline{DLE} = L$ , $\overline{A}/D = H$ )	R1 = 270 Ω, R2 = 470 Ω	300 pF	S1 Closed§		11	18	ns
<sup>t</sup> pd	Propagation time, $\overline{ALE}$ low to $\overline{ADx}$ (A/D = L)	R1 = 270 Ω, R2 = 470 Ω	300 pF	S1 Closed§		10	18	ns
<sup>t</sup> pd	Propagation time, $\overline{DLE}$ low to $\overline{ADx}$ ( $\overline{A}/D = H$ )	R1 = 270 Ω, R2 = 470 Ω	300 pF	S1 Closed§		11	18	ns
<sup>t</sup> pd	Propagation time, $\overline{A}/D$ to $\overline{ADx}$	R1 = 270 Ω, R2 = 470 Ω	300 pF	S1 Closed§		10	16	ns
tpd	Propagation time, ACLK to IDEQ	RL = 500 Ω	50 pF	¶		12	20	ns
t <sub>pd</sub>	Propagation time, ACLK to SSEQ	RL = 500 Ω	50 pF	¶		12	18	ns
tpd	Propagation time, IDx to IDEQ	RL = 500 Ω	50 pF	¶		12	22	ns
tpd	Propagation time, IDx to SSEQ	RL = 500 Ω	50 pF	¶		12	22	ns
t <sub>en</sub>	Enable time, AEN to Ax	R1 = 500 Ω, R2 = 500 Ω	50 pF	ŧ		10	16	ns
t <sub>en</sub>	Enable time, $\overline{\text{DEN}}$ to Dx	R1 = 500 Ω, R2 = 500 Ω	50 pF	Ŧ		10	16	ns
ten	Enable time, ADEN to ADx	R1 = 270 Ω, R2 = 470 Ω	300 pF	§		10	18	ns
<sup>t</sup> dis	Disable time, AEN to Ax	R1 = 500 Ω, R2 = 500 Ω	50 pF	Ŧ		6	10	ns
<sup>t</sup> dis	Disable time, DEN to Dx	R1 = 500 Ω, R2 = 500 Ω	50 pF	Ŧ		6	10	ns
<sup>t</sup> dis	Disable time, ADEN to ADx	R1 = 270 Ω, R2 = 470 Ω	50 pF	§		6	10	ns

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V,  $T_A = 25^{\circ}$ C.

<sup>‡</sup> See Parameter Measurement Information for load circuit (3-state outputs, A15–A0, D15–D0) and voltage waveforms.

§See Parameter Measurement Information for load circuit (NuBus™ Interface, AD15–AD0) and voltage waveforms. ¶See Parameter Measurement Information for load circuit (bi-state totem-pole outputs, SSEQ, IDEQ) and voltage waveforms.



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- NOTES: A. Cl includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal condition such that the output is high except when disabled by the output control.
  - C. C. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_{f}$  =  $t_{f}$  = 2 ns, duty cycle = 50%  $\,$
  - D. The outputs are measured one at a time with one transition per measurement.

#### Figure 1



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### **APPLICATION INFORMATION**

Figure 2. Typical Nubus™ Interface





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### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74BCT2420FN	OBSOLETE	PLCC	FN	68		TBD	Call TI	Call TI	
SN74BCT2420FNR	OBSOLETE	PLCC	FN	68		TBD	Call TI	Call TI	

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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